

Please add the following new claims:

- 23. An integrated circuit including a transistor, said transistor comprising:
- a control terminal extending above a plane of semiconductor material, said control terminal having two side portions and a top portion covered by an insulating layer; and
  - first and second terminals on either side of said control terminal, said first and second terminals extending above said plane of semiconductor material such that top portions of said first and second terminals are substantially coplanar with said insulating layer covering said top portion of said control terminal.
24. The circuit of Claim 23, wherein said insulating layer covering said top portion of said control terminal comprises alternating sub-layers of first and second insulating materials.
25. The circuit of Claim 24, wherein said first insulating material is silicon oxide and said second insulating material is silicon nitride.
26. The circuit of Claim 23, wherein said control terminal is a gate electrode of a field effect transistor and said first and second terminals comprise local interconnections to drain and source regions of said transistor.
27. An integrated circuit including a transistor, said transistor comprising:
- a gate stack extending above a plane of semiconductor material, said gate stack comprising a gate dielectric and a gate electrode over said gate dielectric, said gate electrode comprising side and top portions covered by insulating material; and
  - local interconnection terminals on opposing sides of said gate stack and abutting said insulating material on said side portions of said gate electrode, said local interconnection terminals extending above said plane of semiconductor

material such that top portions of said local interconnection terminals are substantially coplanar with said insulating material covering said top portion of said gate electrode.

28. The circuit of Claim 27, wherein said insulating material covering said top portion of said control terminal comprises alternating layers of first and second insulating materials.

29. The circuit of Claim 28, wherein said first insulating material is silicon oxide and said second insulating material is silicon nitride.

30. The circuit of Claim 27, wherein each of said local interconnection terminals includes a column of insulating material. —

Claims 18-30 are now pending in this Application. Applicant respectfully requests entry and consideration of these claims.

If the Examiner has any questions or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

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Respectfully submitted,



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